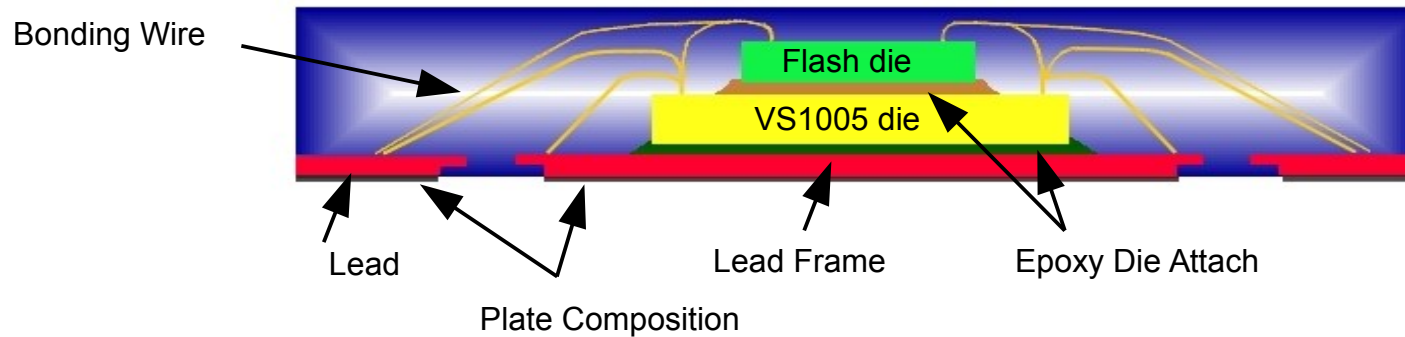


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Rev: 1.1

# Cross-Section View VS1205GF/VS1005GF/VS8005GF 88pin LF GA (ROHS)



## SUBSTRATE (Lead Frame)

Plate composition

100% Sn

Plate thickness

300-800 micro inches

## Material

Lead Frame

HDL (10X10) LF

Epoxy Die Attach

Bottom (VS1005 die) CRM1066C

Top (Flash die) QMI-536

Bonding Wire

GOLD WIRE 25 MICRONS

Mold Compound

EME G770HP